

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|---------------------|
| 1 | 33 | "5610442" | USPAT | 2003/06/18 11:25 |
| 2 | 231 | 438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:40 |
| 3 | 105 | (438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:56 |
| 4 | 19 | ((438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold)) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:39 |
| 5 | 40 | 438/124.ccls. and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:34 |
| 6 | 7 | (438/124.ccls. and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:07 |
| 7 | 4347 | (chip or die) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:06 |
| 8 | 233 | ((chip or die) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:45 |
| 9 | 1 | 257/166.ccls. and (heat adj (sink or spreader)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:55 |
| 10 | 193 | 257/666.ccls. and (heat adj (sink or spreader)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:56 |
| 11 | 102 | (257/666.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 11:56 |
| 12 | 1165 | (chip or die) and ((laser or ablate or ablatting or remove or removal) near (encapsulant or encapsulate or mold)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:07 |
| 13 | 59 | ((chip or die) and ((laser or ablate or ablatting or remove or removal) near (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:14 |
| 14 | 260 | 257/796.ccls. and (heat adj (sink or spreader)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:19 |

| | | | | |
|----|------|------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|---------------------|
| 15 | 128 | ((laser or ablate or ablatting) near (encapsulant or encapsulate or mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:52 |
| 16 | 88 | ((laser or ablate or ablatting) near (encapsulant or encapsulate or mold)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 14:32 |
| 17 | 27 | ((laser or ablate or ablatting) near (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (chip or die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:53 |
| 18 | 1858 | (laser or ablate or ablatting) with (encapsulant or encapsulate or mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:53 |
| 19 | 607 | ((laser or ablate or ablatting) with (encapsulant or encapsulate or mold)) and (chip or die) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 12:53 |
| 20 | 418 | ((laser or ablate or ablatting) with (encapsulant or encapsulate or mold)) and (chip or die)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 13:05 |
| 21 | 1 | ("6432840").PN. | USPAT | 2003/06/18 13:24 |
| 22 | 1 | ("6297543").PN. | USPAT | 2003/06/18 13:27 |
| 23 | 1 | ("5723900").PN. | USPAT | 2003/06/18 14:14 |
| 24 | 1 | ("6544814").PN. | USPAT | 2003/06/18 14:31 |
| 25 | 53 | (laser near (watts or W)) and (Encapsualnt or encapsulate or mold) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 14:32 |
| 26 | 25 | ((laser near (watts or W)) and (Encapsualnt or encapsulate or mold)) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 16:04 |
| 27 | 1 | ("5723900").PN. | USPAT | 2003/06/18 15:54 |
| 28 | 1 | ("6297543").PN. | USPAT | 2003/06/18 15:21 |
| 29 | 1 | ("6369455").PN. | USPAT | 2003/06/18 16:01 |
| 31 | 37 | (encapsulant or encapsulat) adj (heat adj (sink or dissipation or spreader)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 16:04 |
| 32 | 335 | (encapsulant or encapsulat) with (heat adj (sink or dissipation or spreader)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 16:04 |
| 33 | 223 | ((encapsulant or encapsulat) with (heat adj (sink or dissipation or spreader))) and (@ad<20000816) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/18 16:05 |